**Internal Specification – Level I**
**Document Number:** IS-009
**Revision:** 05
**Effective Date:** 11/25/2025
**Point of Contact:** Brad Toone
**Title:** PCB SME

# Immersion Gold – Electroless Nickel Specification

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## PURPOSE & SCOPE

This Internal Specification (IS-009) standardizes the thickness/tolerance of gold on Electroless Nicle Immersion Gold (ENIG) products.

IS-009 shall take precedence over all existing L3 Harris Communications Systems West (CSW) drawings, policies or procedures specifying ENIG plating. This specification is effective 1 March 2004 and shall be subject to inspection acceptance on affected product after said date.

## INTERNAL SPECIFICATION

### 1. SPECIFICATION

IS-009 standardizes the requirements for ENIG as follows:

- Electroless Nickel / Immersion Gold Thickness: In accordance with IPC-4552.
- Immersion Gold: Maximum thickness shall not exceed 5 micro-inches.
- Adhesion: In accordance with IPC-4552.

### 2. IMPLEMENTATION

- IS-009 shall be referenced on all Printed Circuit Board (PCB) drawings released after 1 March 2004.
- Released PCB drawings and parts lists will not be revised.
- IS-009 will be provided to all approved PCB suppliers.

**END OF DOCUMENT**

## DOCUMENT INFORMATION

| | |
|---|---|
| **Responsible Organization:** | Quality |
| **Function/Sub-function:** | Hardware Quality Assurance |
| **Governing Document:** | Y-001, L3 Technologies CSW Quality Manual |
| **Subordinate Document(s):** | NA |
| **Related Documents(s)** | IPC-4552, Specification for Electroless Nickel/Immersion Gold (ENIG) Plating for Printed Circuit Boards |
| **Approval Requirements:** | Document Control Administration<br>Quality Representative (Director, Quality)<br>Operations Representative (PCB SME)<br>Engineering Representative (Manager, PCB Design)<br>Manager, Configuration Management |
| **Review Requirements:** | DCMA |

## REVISION HISTORY SUMMARY

| Revision # | Reason for update/revision | Date |
|---|---|---|
| New -01 | Initial release through Rev. 01 | 05/02/2006 |
| 02 | 24-month review. Put into new format. No process changes made. | 03/13/2009 |
| 03 | 24-month review. No changes made. | 07/26/2011 |
| 04 | 24-month review. Modified approval requirements. No other changes made. | 9/29/2014 |
| 05 | Update format. No technical changes. | 11/25/2025 |